



ISO100

Optically-Coupled Linear ISOLATION AMPLIFIER

FEATURES

- EASY TO USE, SIMILAR TO AN OP AMP $V_{OUT}/I_{IN} = R_F$, Current Input $V_{OUT}/V_{IN} = R_F/R_{IN}$, Voltage Input
- 100% TESTED FOR BREAKDOWN: 750V Continuous Isolation Voltage
- ULTRA-LOW LEAKAGE: 0.3µA, max, at 240V/60Hz
- WIDE BANDWIDTH: 60kHz
- 18-PIN DIP PACKAGE

DESCRIPTION

The ISO100 is an optically-coupled isolation amplifier. High accuracy, linearity, and time-temperature stability are achieved by coupling light from an LED back to the input (negative feedback) as well as forward to the output. Optical components are carefully matched and the amplifier is actively laser-trimmed to assure excellent tracking and low offset errors.

The circuit acts as a current-to-voltage converter with a minimum of 750V (2500V test) between input and output terminals. It also effectively breaks the gal-vanic connection between input and output commons as indicated by the ultra-low 60Hz leakage current of $0.3\mu A$ at 250V. Voltage input operation is easily achieved by using one external resistor.

Versatility along with outstanding DC and AC performance provide excellent solutions to a variety of challenging isolation problems. For example, the ISO100 is capable of operating in many modes, including: noninverting (unipolar and bipolar) and inverting (unipolar and bipolar) configurations. Two precision current sources are provided to accomplish bipolar operation. Since these are not required for unipolar operation, they are available for external use (see Applications section).

APPLICATIONS

- INDUSTRIAL PROCESS CONTROL Transducer Sensing (Thermocouples, RTD, Pressure Bridges) 4mA to 20mA Loops Motor and SCR Control Ground Loop Elimination
- BIOMEDICAL MEASUREMENTS
- TEST EQUIPMENT
- DATA ACQUISITION

Designs using the ISO100 are easily accomplished with relatively few external components. Since V_{OUT} of the ISO100 is simply $I_{IN}R_F$, gains can be changed by altering one resistor value. In addition, the ISO100 has sufficient bandwidth (DC to 60kHz) to amplify most industrial and test equipment signals.



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SPECIFICATIONS

ELECTRICAL

At T_{A} = +25°C and $\pm V_{CC}$ = 15VDC, unless otherwise specified.

		ISO100AP		ISO100BP		ISO100CP					
PARAMETER	CONDITIONS	MIN	TYP	МАХ	MIN	TYP	MAX	MIN	ТҮР	МАХ	UNITS
ISOLATION Voltage Rated Continuous, AC peak or DC ⁽¹⁾ Test Breakdown, DC Rejection ⁽²⁾ DC AC Impedance Leakage Current	10s $R_{IN} = 10k\Omega$, Gain = 100 60Hz, 480V, $R_F = 1M\Omega$ $R_{IN} = 10k\Omega$, Gain = 100 240Vrms, 60Hz	750 2500	5 146 400 108 10 ¹² 2.5	0.3	* *	* * * *	*	* *	* * * *	*	V V dB pA/V dB Ω pF μA, rms
OFFSET VOLTAGE (RTI) Input Stage (V _{OSI}) Initial Offset vs Temperature vs Input Power Supplies vs Time Output Stage (V _{OSO}) Initial Offset vs Temperature vs Output Power Supplies vs Time Common-Mode Rejection Ratio ⁽²⁾	60Hz, R _F = 1MΩ R _{IN} = 10kΩ, Gain = 100		1 1 3 90	500 5 105 500 5 105		* * *	300 2 * 300 2 *		*	200 2 * 200 2 *	μV μV/°C dB μV/kHr μV/°C dB μV/kHr nA/V dB
Common-Mode Range		±10			*			*			V
REFERENCE CURRENT SOURCES Magnitude Nominal vs Temperature vs Power Supplies Matching Nominal vs Temperature vs Power Supplies Compliance Voltage Output Resistance		-10	12 0.3 50 150 0.3 2 x 10 ⁹	12.5 300 3 +15	*	* * * * *	* * * *	*	* * * * *	* 150 *	µA ppm/°C nA/V nA ppm/°C nA/V V Ω
FREQUENCY RESPONSE Small Signal Bandwidth Full Power Bandwidth Slew Rate Settling Time	Gain = 1V/μΑ Gain = 1V/μΑ, V _O = ±10V 0.1%	0.22	60 5 0.31 100		*	* * * *		*	* * * *		kHz kHz V/μs μs
TEMPERATURE RANGE Specification Operating Storage	UNIPOL	-25 -40 -40 AR OPE	RATION	+85 +100 +100	* * *		* * *	* * *		* * *	°C °C °C
GENERAL PARAMETERS											
Input Current Range Linear Operation Without Damage Input Impedance Output Voltage Swing Output Impedance	$R_L = 2k\Omega$, $R_F = 1M\Omega$ DC, Open-Loop	-20 -1 -10	0.1 1200	-0.02 +1 0	* * *	*	* *	* *	*	* *	μA mA Ω V Ω
GAIN Initial Error (adjustable to zero) vs Temperature vs Time Nonlinearity ⁽³⁾	$V_{O} = R_{F} (I_{IN})$		2 0.03 0.05 0.1	5 0.07 0.4		1 0.01 * 0.03	2 0.05 0.1		1 0.005 * 0.02	2 0.03 0.07	% of FS %/°C %/kHr %
CURRENT NOISE 0.01Hz to 10Hz 10Hz 100Hz 1kHz	I _{IN} = 0.2μΑ		20 1 0.7 0.65			* * *			* * *		pAp-p pA/√Hz pA/√Hz pA/√Hz



SPECIFICATIONS (CONT)

ELECTRICAL

At $T_A = +25^{\circ}C$ and $\pm V_{CC} = 15VDC$, unless otherwise specified.

		ISO100AP		ISO100BP		ISO100CP					
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
INPUT OFFSET CURRENT (I _{os}) Initial Offset vs Temperature vs Power Supplies vs Time			1 0.05 0.1 100	10		* * * *	*		* * * *	*	nA nA/°C nA/V pA/kHr
POWER SUPPLIES Input Stage Voltage (rated performance) Voltage (derated performance) Supply Current Output Stage Voltage (rated performance) Voltage (derated performance)	I _{IN} = -0.02μA I _{IN} = -20μA	±7 ±7	±15 ±1.1 +8, -1.1 ±15	±18 ±2 +13, -2 ±18	*	* * *	* * *	*	* * *	* * *	V V mA mA V V
Supply Current Short Circuit Current Limit	V _O = 0		±1.1	±2 ±40		*	* *		*	*	mA mA
	BIPOL	AR OPE	RATION	-		1	1		1	1	
GENERAL PARAMETERS Input Current Range Linear Operation Without Damage Input Impedance Output Voltage Swing Output Impedance	$R_L = 2k\Omega, R_F = 1M\Omega$	-10 -1 -10	0.1	+10 +1 +10	* *	*	* *	* * *	*	* *	μA mA Ω V
GAIN Initial Error (Adjustable To Zero) vs Temperature vs Time Nonlinearity ⁽³⁾	$V_{O} = R_{F} (I_{IN})$		2 0.03 0.05 0.1	5 0.07 0.4		1 0.01 * 0.03	2 0.05 0.1		1 0.005 * 0.02	2 0.03 0.07	% of FS %/°C %/kHr %
CURRENT NOISE 0.01Hz to 10Hz 10Hz 100Hz 1kHz	Ι _{IN} = 0.2μΑ		1.5 17 7 6			* * * *			* * * *		nA, p-p pA/√Hz pA/√Hz pA/√Hz
INPUT OFFSET CURRENT (I _{OS} , bip Initial Offset vs Temperature vs Power Supplies vs Time	olar ⁽⁴⁾)		40 250	200 3 0.7		20 *	70 2 *		10 *	35 1 *	nA nA/°C nA/V pA/kHr
POWER SUPPLIES Input Stage Voltage (rated performance) Voltage (derated performance) Supply Current	I _{IN} = +10μΑ I _{IN} = -10μΑ	±7	±15 +2, -1.1 +8, -1.1	±18 +3, -2 +13, -2	*	* * *	* * *	*	* * *	* * *	V V mA mA
Voltage (rated performance) Voltage (derated performance) Supply Current Short Circuit Current Limit	V ₀ = 0	±7	±15 ±1.1	±18 ±2 ±40	*	*	* *	*	*	* * *	V V mA mA

* Same as ISO100AP.

NOTES: (1) See Typical Performance Curves for temperature effects. (2) See Theory of Operation section for definitions. For dB see Ex. 2, CM and HV errors. (3) Nonlinearity is the peak deviation from a "best fit" straight line expressed as a percent of full scale output. (4) Bipolar offset current includes effects of reference current mismatch and unipolar offset current.

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PIN CONFIGURATION



ORDERING INFORMATION

PRODUCT	PACKAGE	TEMPERATURE RANGE
ISO100AP	18-Pin Bottom-Braze DIP	−25°C to +85°C
ISO100BP	18-Pin Bottom-Braze DIP	−25°C to +85°C
ISO100CP	18-Pin Bottom-Braze DIP	−25°C to +85°C

ABSOLUTE MAXIMUM RATINGS

Supply Voltages	±18V
Isolation Voltage, AC pk or DC	
Input Current	±1mA
Storage Temperature Range	–40°C to +100°C
Lead Temperature (soldering, 10s)	+300°C
Output Short-Circuit Duration	Continuous to Ground

PACKAGE INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾
ISO100AP	18-Pin Bottom-Braze DIP	220
ISO100BP	18-Pin Bottom-Braze DIP	220
ISO100CP	18-Pin Bottom-Braze DIP	220

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.



TYPICAL PERFORMANCE CURVES

At T_A = +25°C, \pm V_{CC} = 15VDC, unless otherwise specified.

















TYPICAL PERFORMANCE CURVES (CONT)

At T_{A} = +25°C, $\pm V_{\text{CC}}$ = 15VDC, unless otherwise specified.





GAIN ERROR vs TEMPERATURE AND ISOLATION VOLTAGE 3 Gain Error (Normalized to +25°C) 2.5 $V_{IM} > V_T$ 2 V_{IM} < V_T 1.5 1 0.5 0 -25 0 25 50 65 75 100 125 TT Temperature (°C)

NOTES: V_T and T_T approximate the threshold for the indicated gain shift. This is caused by the properties of the optical cavity. T_T \approx +65°C. V_T \approx 200VDC. Shift does V_{IM} = Isolation-Mode Voltage V_T = Threshold Voltage T_T = Threshold Temperature

 $T_{T}\approx$ +65°C, $V_{T}\approx$ 200VDC. Shift does not occur fo AC voltages.





THEORY OF OPERATION

The ISO100 is fundamentally a unity gain current amplifier intended to transfer small signals between electrical circuits separated by high voltages or different references. In most applications, an output voltage is obtained by passing the output current through the feedback resistor (R_F).

The ISO100 uses a single light emitting diode (LED) and a pair of photodiode detectors coupled together to isolate the output signal from the input.

Figure 1 shows a simplified diagram of the amplifier. I_{REF1} and I_{REF2} are required only for bipolar operation to generate a midscale reference. The LED and photodiodes (D_1 and D_2) are arranged such that the same amount of light falls on each photodiode. Thus, the currents generated by the diodes match very closely. As a result, the transfer function depends upon optical match rather than absolute performance. Laser-trimming of the components improves matching and enhances accuracy, while negative feedback improves linearity. Negative feedback around A_1 occurs through the optical path formed by the LED and D_1 . The signal is transferred across the isolation barrier by the matched light path to D_2 .

The overall isolation amplifier is noninverting (a positive going input produces a positive going output).

INSTALLATION AND OPERATING INSTRUCTIONS

UNIPOLAR OPERATION

In Figure 1, assume a current, I_{IN} , flows out of the ISO100 (I_{IN} must be negative in unipolar operation). This causes the voltage at pin 15 to decrease. Because the amplifier is inverting, the output of A_1 increases, driving current through

the LED. As the LED light output increases, D_1 responds by generating an increasing current. The current increases until the sum of the currents in and out of the input node (–Input to A_1) is zero. At that point, the negative feedback through D_1 has stabilized the loop, and the current I_{D1} equals the input current plus the bias current. As a result, no bias current flows in the source. Since D_1 and D_2 are matched ($I_{D1} = I_{D2}$), I_{IN} is replicated at the output via D_2 . Thus, A_1 functions as a unity-gain current amplifier, and A_2 is a current-to-voltage converter, as described below.

Current produced by D_2 must either flow into A_2 or R_F . Since A_2 is designed for low bias current ($\approx 10nA$), almost all of the current flows through R_F to the output. The output voltage then becomes:

$$V_{O} = (I_{D2})R_{F} = (I_{D1} \pm I_{OS})R_{F} \approx -(-I_{IN})R_{F} = I_{IN}R_{F}$$
 (1)

where, I_{OS} is the difference between A_1 and A_2 bias currents. For input voltage operation I_{IN} can be replaced by a voltage source (V_{IN}) and series resistor (R_{IN}), since the summing node of the op amp is essentially at ground. Thus, $I_{IN} = V_{IN}/R_{IN}$.

Unipolar operation does have some constraints, however. In this mode the input current must be negative so as to produce a positive output voltage from A_1 to turn the LED on. A current more negative than 20nA is necessary to keep the LED turned on and the loop stabilized. When this condition is not met, the output may be indeterminant. Many sensors generate unidirectional signals, e.g., photoconductive and photodiode devices, as well as some applications of thermocouples. However, other applications do require bipolar operation of the ISO100.

BIPOLAR OPERATION

To activate the bipolar mode, reference currents as shown in Figure 1 are attached to the input nodes of the op amps. The input stage stabilizes just as it did in unipolar operation.



FIGURE 1. Simplified Block Diagram of the ISO100.



Assuming $I_{IN} = 0$, the photodiode has to supply all the I_{REF1} current. Again, due to symmetry, $I_{D1} = I_{D2}$. Since the two references are matched, the current generated by D_2 will equal I_{REF2} . This results in no current flow in R_F , and the output voltage will be zero. When I_{IN} either adds or subtracts current from the input node, the current D_1 will adjust to satisfy $I_{D1} = I_{IN} + I_{REF1}$. Because I_{REF1} equals I_{REF2} and I_{D1} equals I_{D2} , a current equal to I_{IN} will flow in R_F . The output voltage is then $V_O = I_{IN}R_F$. The range of allowable I_{IN} is limited. Positive I_{IN} can be as large as I_{REF1} (10.5µA, min). At this point, D_1 supplies no current and the loop opens. Negative I_{IN} can be as large as that generated by D_1 with maximum LED output (recommended 10µA, max).

DC ERRORS

Errors in the ISO100 take the form of offset currents and voltages plus their drifts with temperature. These are shown in Figure 2.

 A_1 and A_2 — assumed to be ideal amplifiers.

 V_{OSO} and V_{OSI} —the input offset voltages of the output and input stage, respectively. V_{OSO} appears directly at the output, but, V_{OSI} appears at the output as

$$V_{OSI} \frac{R_F}{R_{IN}}, \qquad (1)$$

see equation (2).

 I_{OS} —the offset current. This is the current at the input necessary to make the output zero. It is equal to the combined effect of the difference between the bias currents of A₁ and A₂ and the matching errors in the optical components in the unipolar mode.

 I_{REF1} and I_{REF2} —reference currents that, when connected to the inputs, enable bipolar operation. The two currents are trimmed, in the bipolar mode, to minimize the $I_{OS BIPOLAR}$ error.

 I_{D1} and I_{D2} —currents generated by each photodiode in response to the light from the LED.

$$A_e$$
—gain error.

$$A_e = |$$
 Ideal gain/Actual gain $| - 1$

The output then becomes:

$$V_{OUT} = R_{F}[(\frac{V_{IN} \pm V_{OS}}{R_{IN}} - I_{REF1} \pm I_{OS})(1 + A_{e}) + I_{REF2}]$$
(2)

The total input referred offset voltage of the ISO100 can be simplified in the unipolar case by assuming that $A_e = 0$ and $V_{IN} = 0$:

$$V_{OUT} \approx R_F \left[\frac{\pm V_{OSI}}{R_{IN}} \pm I_{OS \ UNIPOLAR}\right] \pm V_{OSO}$$
(3)

This voltage is then referred back to the input by dividing by R_F/R_{IN} .

Example 1. Refer to Figure 2 and Electrical Specifications Table.

= +35nA

Given:
$$I_{OS BIPOLAR}$$

 $R_{IN} = 100k\Omega$
 $R_F = 1M\Omega$ (gain = 10)
 $V_{OSI} = +200\mu V$
 $V_{OSO} = +200\mu V$

Find: The total offset voltage error referred to the input and output when $V_{IN} = 0V$.

$$= \{ [\pm V_{\text{OSI}} \pm R_{\text{IN}} (I_{\text{OS BIPOLAR}}) - R_{\text{IN}} (I_{\text{REF 1}})] \\ [1 + A_e] + R_{\text{IN}} I_{\text{REF 2}} \} \pm V_{\text{OSO}} / (R_F / R_{\text{IN}})$$

 $= \{ [+200\mu V + 100k\Omega (35nA) - 100k\Omega (12.5\mu A)] \\ [1.02] + 100k\Omega (12.5\mu A] \} + 200\mu V/(1M\Omega/100k\Omega) \\ = \{ [0.2mV + 3.5mV - 1.25V] \\ [1.02] + 1.25V \} + 0.02mV$

$$= -21.2$$
mV

$$=$$
 V_{OS} total RTI x R_F/R_{IN}

$$= -21.2$$
mV x 10

$$= -212mV$$



FIGURE 2. Circuit Model for DC Errors in the ISO100.



NOTE: This error is dominated by IOS BIPOLAR and the reference current times the gain error (which appears as an offset). The error for unipolar operation is much lower. The error due to offset current can be zeroed using circuits shown in Figures 6 and 7. The gain error is adjusted by trimming either R_F or R_{IN}.

COMMON-MODE AND HIGH VOLTAGE ERRORS

Figure 3 shows a model of the ISO100 that can be used to analyze common-mode and high voltage behavior.



FIGURE 3. High Voltage Error Model.

Definitions of CMR and IMR

I_{OS} is defined as the input current required to make the ISO100's output zero. CMRR and IMRR in the ISO100 are expressed as conductances. CMRR defines the relationship between a change in the applied common-mode voltage $\left(V_{CM}\right)$ and the change in I_{OS} required to maintain the amplifier's output at zero:

$$CMRR (I-mode) = \Delta I_{OS} / \Delta V_{CM} \text{ in } nA / V$$
(5)

CMRR (V-mode) =
$$\left[\frac{\Delta I_{OS}}{\Delta V_{CM}}\right] R_{IN} = \frac{\Delta V_{ERR CM}}{\Delta V_{CM}} in V/V$$
 (6)

IMRR defines the relationship between a change in the applied isolation mode voltage (V_{IM}) and the change in I_{OS} required to maintain the amplifier's output to zero:

IMRR (I-mode) =
$$\frac{\Delta I_{OS}}{\Delta V_{IM}}$$
 in pA/V (7)

IMRR (V-mode) =
$$\left[\frac{\Delta I_{OS}}{\Delta V_{IM}}\right] R_{IN} = \frac{\Delta V_{ERR IM}}{\Delta V_{IM}} \text{ in } V/V (8)$$

CMRR and IMRR in V/V are a function of R_{IN}.

 V_{IM} is the voltage between input common and output common.

 V_{CM} is the common-mode voltage (noise that is present on both input lines, typically 60Hz).

V_{ERR} is the equivalent error signal, applied in series with the input voltage, which produces an output error identical to that produced by application of V_{CM} and V_{IM} .

CMRR and IMRR are the common-mode and isolationmode rejection ratios, respectively.

Total Capacitance (C_1 and C_2) is distributed along the isolation barrier. Most of the capacitance is coupled to low impedance or noncritical nodes and affects only the leakage current. Only a small capacitance (C_2) couples to the input of the second stage, and contributes to IMRR.

Example 2. Refer to Figure 3 and Electrical Specification Table.

Given:
$$V_{CM} = 1$$
VAC peak at 60Hz, $V_{IM} = 200$ VDC,
CMRR = 3nA/V, IMRR = 5pA/V,
 $R_{IN} = 100$ k Ω , $R_F = 1$ M Ω
(Gain = 10)

Find: The error voltage referred to the input and output when $V_{IN} = 0V$

$$\begin{split} V_{\text{ERR RTI}} &= (V_{\text{CM}})(\text{CMRR})(\text{R}_{\text{IN}}) + (V_{\text{IM}})(\text{IMRR})(\text{R}_{\text{IN}}) \\ &= 1V \; (3nA/V)(100k\Omega) \\ &+ 200V \; (5pA/V)(100k\Omega) \\ &= 0.3mV + 0.1mV \\ &= 0.4mV \\ V_{\text{ERR RTO}} &= V_{\text{ERR RTI}} \; (\text{R}_{\text{F}}/\text{R}_{\text{IN}}) \end{split}$$

ERR RTO

= 0.4 mV (10)=4mV (with DC IMRR)

NOTE: This error is dominated by the CMRR term.

For purposes of comparing CMRR and IMRR directly with dB specifications, the following calculations can be performed:

CMRR in V/V = CMRR (I-mode)(
$$R_{IN}$$
)
= 3nA/V (100k Ω) = 0.3mV/V
CMR = 20 LOG (0.3mV/V) = -70dB at 60Hz
IMRR in V/V = IMRR (I-mode)(R_{IN}) = 5pA/V(100k Ω)
= 0.5 μ V/V
IMR = 20 LOG (0.5 x 10⁻⁶V/V) = -126dB at DC

Example 3.

In Example 3, V_{IM} is an AC signal at 60Hz and

$$IMRR = \frac{400pA}{V}$$

$$\begin{split} V_{\text{ERR RTI}} &= V_{\text{ERR CM}} + V_{\text{ERR IM}} \\ &= 0.3 \text{mV} + 200 \text{V} \ (400 \text{pA/V})(100 \text{k}\Omega) \\ &= 8.3 \text{mV} \end{split}$$

 $V_{ERR RTO} = 83mV$ (with AC IMRR)



Example 4.

Given: Total error RTO from Examples 1 and 3 as 378mV worst case.

Find: Percent error of +10V full scale output

% Error =
$$\frac{V_{ERR TOTAL}}{V_{FS}} \times 100\%$$

= $\frac{378 \text{mV}}{10 \text{V}} \times 100\%$
= 3.78%

NOISE ERRORS

Noise errors in the unipolar mode are due primarily to the optical cavity. When the full 60kHz bandwidth is not needed, the output noise of the ISO100 can be limited by either a capacitor, C_F , in the feedback loop or by a low-pass filter following the output. This is shown in Figure 4. Noise in the bipolar mode is due primarily to the reference current sources, and can be reduced by the low-pass filters shown in Figure 5.



FIGURE 4. Two Circuit Techniques for Reducing Noise in the Unipolar Mode.



FIGURE 5. Circuit Techniques for Reducing Noise from the Current Sources in the Bipolar Mode.

OPTIONAL ADJUSTMENTS

There are two major sources of offset error: offset voltage and offset current. V_{OSI} and V_{OSO} of the input and output amplifiers can be adjusted independently using external potentiometers. An example is shown in Figure 17. Note that V_{OSO} (500µV, max) appears directly at the output, but V_{OSI} appears at the output multiplied by gain (R_F/R_{IN}). In general, V_{OS} is small compared to the effect of I_{OS} (see Example 1). To adjust for I_{OS} use a circuit which intentionally unbalances the offset in one direction and then allows for adjustment back to zero.

Figure 6 shows how to adjust unipolar errors at zero input. The unipolar amplifier can be used down to zero input if it is made to be "slightly bipolar." By sampling the reference current with R_5 and R_6 , the minimum current required to keep the input stage in the linear region of operation can be established. R_7 and R_8 are adjusted to cancel the offset created in the input stage. This brings the output to zero, when the input is zero. Although the amplifier can now operate down to zero input voltage, it has only a small portion of the current drain and noise that the true bipolar configuration would have.

Adjusting the bipolar errors is illustrated in Figure 7. Each of the errors are adjusted in turn. With V_{IN} = "open,", I_{OS} is trimmed by adjusting R_{10} to make the output zero. R_G is then adjusted to trim the gain error. The effects of offset voltage are removed by adjusting R_{14} .



FIGURE 6. Adjusting the Unipolar Amplifier Errors at Zero Input.



FIGURE 7. Adjusting the Bipolar Errors.

BASIC CIRCUIT CONNECTIONS



FIGURE 8. Unipolar Noninverting.



FIGURE 9. Bipolar Noninverting.



FIGURE 10. Unipolar Inverting.



FIGURE 11. Bipolar Inverting.

APPLICATION INFORMATION

The small size, low offset and drift, wide bandwidth, ultralow leakage, and low cost, make the ISO100 ideal for a variety of isolation applications. The basic mode of operation of the ISO100 will be determined by the type of signal and application.

Major points to consider when designing circuits with the ISO100.

- 1. Input Common (pin 18) and –In (pin 17) should be grounded through separate lines. The Input Common can carry a large DC current and may cause feedback to the signal input.
- 2. Use shielded or twisted pair cable at the input for long lines.
- 3. Care should be taken to minimize external capacitance across the isolation barrier.



- 4. The distance across the isolation barrier, between external components and conductor patterns, should be maximized to reduce leakage and arcing.
- 5. Although not an absolute requirement, the use of conformally-coated printed circuit boards is recommended.
- 6. When in the unipolar mode, the reference currents (pins 8 and 16) must be terminated. $I_{\rm IN}$ should be greater than 20nA to keep internal LED on.
- 7. The noise contribution of the reference currents will cause the bipolar mode to be noisier than the unipolar mode.
- 8. The maximum output voltage swing is determined by $I_{\rm IN}$ and $R_{\rm F}.$

$$V_{SWING} = I_{IN MAX} X R_F$$

9. A capacitor (about 3pF) can be connected across R_F to compensate for peaking in the frequency response. The peaking is caused by the pole generated by R_F and the capacitance at the input of the output amplifier.

Figure 12 through 18 show applications of the ISO100.



FIGURE 12. Two-Port Isolation Photodiode Amplifier Unipolar.



FIGURE 13. Precision Bridge Isolation Amplifier (Unipolar).





FIGURE 14. Three-Port Isolation Thermocouple Amplifier (Bipolar).



FIGURE 15. Isolated Test Equipment Amplifier (Unipolar with Offsetting).



FIGURE 16. Isolated 4mA to 20mA Transmitter (Example of an isolated voltage controlled current source).





FIGURE 17. Four-Port Isolated Summing Amplifier (Unipolar).





FIGURE 18. Multiple Channel Isolation Amplifier (Bipolar) with Programmable Gain (useful in data acquisition systems).



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
ISO100AP	NRND	CDIP BB	JDG	18	TBD	Call TI	Call TI
ISO100BP	NRND	CDIP BB	JDG	18	TBD	Call TI	Call TI
ISO100CP	NRND	CDIP BB	JDG	18	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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